



3.0A SURFACE MOUNT ULTRA-FAST RECTIFIER

Product Summary (@T_A = +25°C)

V _{RRM} (V)	I _O (A)	V _F (V)	Ι _R (μΑ)
1,000	3	1.8	10

Description

3.0A Surface Mount Glass Passivated Rectifier in SMC package offers high current capability and ultra-fast recovery time for high efficiency. Designed with glass passivated die construction for high reliability, this device is ideal for applications such as:

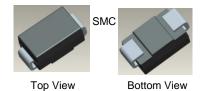
- Power Supplies
- Lighting Ballasts

Features and Benefits

- Glass Passivated Die Construction
- High Current Capability
- Ultra-Fast Recovery Time for High Efficiency
- Maximum Operating Junction Temperature of +175°C
- Lead Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: SMC
- Case Material: Molded Plastic.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Lead-Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 (3)
- Polarity: Cathode Band or Cathode Notch
- Weight: 0.21 grams (Approximate)



Ordering Information (Note 4)

Part Number	Case	Packaging
US3M-13	SMC	3,000/Tape & Reel

1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definations of Halogen- and Antimony-free, "Green"

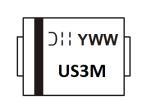
and Lead-free. 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and

<1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

Notes:



SMC

US3M = Product Type Marking Code Clinic = Manufacturer's Code Marking YWW = Date Code Marking Y = Last Digit of Year (ex: 4 for 2014) WW = Week Code 01 to 53



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

or capacitance load, derate current by 20%.					
Characteristic		Symbol	Value	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _{RWM} V _R	1,000	V	
RMS Reverse Voltage		V _{R(RMS)}	700	V	
Average Rectified Output Current	@ T _T = +75°C	lo	3.0	Α	
Non-Repetitive Peak Forward Surge Co Single Half Sine-Wave Superimposed of		I _{FSM}	120	А	

Thermal Characteristics

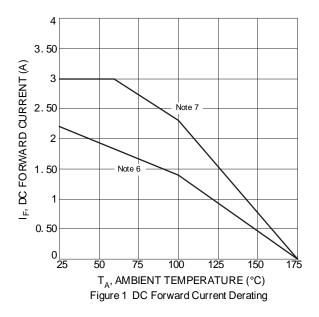
Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal (Note 7)	$R_{\theta JT}$	26	°C/W
Operating and Storage Temperature Range	$T_{J_i} T_{STG}$	-65 to +175	°C

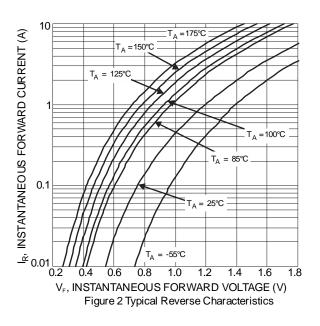
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	V _{(BR)R}	1,000	_	_	V	I _R =10µA
Forward Voltage	VF		1.5	1.8	V	I _F = 3.0A
Leakage Current (Note 5)	I _R	_	2.2 14	10 500	μA	V _R =1,000V, T _A = +25°C V _R =1,000V, T _A = +125°C
Reverse Recovery Time	trr		70	85	ns	$I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A$
Total Capacitance	Ст	—	25	—	pF	V _R = 4V, f =1.0MHz
Notes: 5. Short duration pulse test used to minimize self-heating effect.						

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Device mounted on FR-4 substrate, 1" x 1", 2oz, single-sided, PC boards with 0.15" x 0.26" copper pads.
 Device mounted on FR-4 substrate, 1" x 1", 2oz, single-sided, PC boards with 0.56" x 0.73" copper pads.







100

80

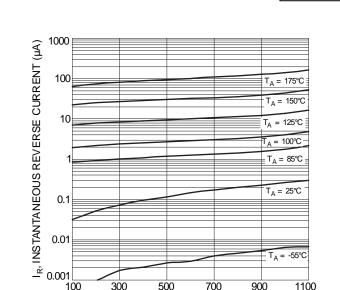
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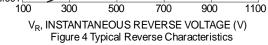
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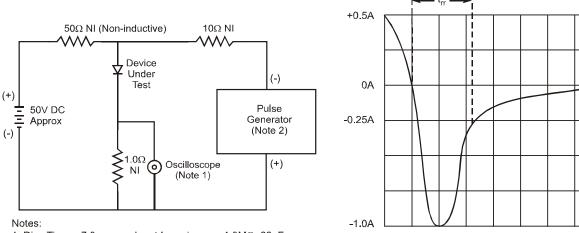
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0∟ 0

C_T, TOTAL CAPACITANCE (pF)







100

f=1MHz

10

V_R, DC REVERSE VOLTAGE (V)

Figure 3 Total Capacitance vs. Reverse Voltage

1. Rise Time = 7.0ns max. Input Impedance = $1.0M\Omega$, 22pF. 2. Rise Time = 10ns max. Input Impedance = 50Ω .

Figure 5 Reverse Recovery Time Characteristic and Test Circuit

Set time base for 50/100 ns/cm

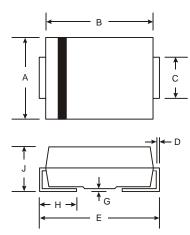
US3M



US3M

Package Outline Dimensions

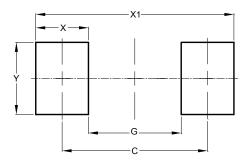
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SMC					
Dim	Min	Max			
Α	5.59	6.22			
В	6.60	7.11			
С	2.75	3.18			
D	0.15	0.31			
ш	7.75	8.13			
G	0.10	0.20			
Н	0.76	1.52			
J	2.00	2.50			
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	6.90
G	4.40
х	2.50
X1	9.40
Y	3.30



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